

PART INFORMATION		
Mfg Item Number	MC08XSF421EKR2	
Mfg Item Name	ESOIC 32 7.5*11*2.3 P.65	
SUPPLIER		
Company Name	Freescale Semiconductor Inc	
Company Unique ID	14-141-7928	
Response Date	2017-06-09	
Response Document ID	00A0K00184D040A1.15	
Contact Name	Freescale Semiconductor Inc	
Contact Title	Product Technical Support	
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URL for Additional Information	www.freescale.com	
DECLARATION		
EU RoHS	Yes	
Pb Free	No	
HalogenFree	Yes	
Plating Indicator	e3	
EU RoHS Exemption(s)	7c-I	
MANUFACTURING		
Mfg Item Number	MC08XSF421EKR2	
Mfg Item Name	ESOIC 32 7.5*11*2.3 P.65	
Version	ALL	
Weight	0.482800	
UoM	g	
Unit Volume	EACH	
J-STD-020 MSL Rating	3	
Peak Processing Temperature	260 C	
Max Time at Peak Temperature	40 seconds	
Number of Processing Cycles	3	

RoHS	
RoHS Directive	2011/65/EU
RoHS Definition	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium
RoHS Legal Definition	Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit identified below. If a homogeneous material within the part(s) contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Companys remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Suppliers Standard Terms and Conditions of Sale applicable to such part(s) shall apply.
RoHS Declaration	4 - Item(s) does not contain RoHS restricted substances per the definition above except for selected exemptions
Supplier Acceptance	Accepted
Signature	Daniel Binyon
Exemption List Version	2012/51/EU
Exemptions in this part	7c-I:Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
List of Freescale Accepted Exemptions	6(a) : Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight 6(b) : Lead as an alloying element in aluminium containing up to 0.4% lead by weight 6(c) : Copper alloy containing up to 4% lead by weight 7(a) : Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead) 7(b) : Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications 7(c)-I : Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound 7(c)-II : Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher 7(c)-III : Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC 7(c)-IV : Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors 15 : Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages

MATERIAL COMPOSITION

Homogeneous Material	Weight	SubstanceClass	Substance	CAS	Exemption	SubstanceWeight	UoM	SubPart PPM	SubPart%		ARTICLEPPM	ARTICLE%
Non-Conductive Epoxy/Adhesive	0.0016						g					
Non-Conductive Epoxy/Adhesive		Plastics/polymers	Proprietary Material-Other Epoxy resins	-		0.00012	g	75000	7.5		248	0.0248
Non-Conductive Epoxy/Adhesive		Plastics/polymers	Crosslinked acrylate polymer	25767-43-5		0.00032	g	200000	20		662	0.0662
Non-Conductive Epoxy/Adhesive		Plastics/polymers	Other polymers	-		0.00012	g	75000	7.5		248	0.0248
Non-Conductive Epoxy/Adhesive		Plastics/polymers	Proprietary Material-Other polymers	-		0.00032	g	200000	20		662	0.0662
Non-Conductive Epoxy/Adhesive		Glass	Silica, vitreous	60676-86-0		0.00072	g	450000	45		1491	0.1491
Bonding Wire, Aluminum	0.0127						g					
Bonding Wire, Aluminum		Metals	Aluminum, metal	7429-90-5		0.0127	g	1000000	100		26304	2.6304
Lead Frame Plating	0.0162						g					
Lead Frame Plating		Lead/Lead Compounds	Lead	7439-92-1		0.00000324	g	200	0.02		6	0.0006
Lead Frame Plating		Metals	Tin, metal	7440-31-5		0.01619676	g	999800	99.98		33547	3.3547
Die Encapsulant, Halogen-free	0.3327						g					
Die Encapsulant, Halogen-free		Solvents, additives, and other materials	Acrylonitrile/Butadiene copolymer, carboxyl terminated (2674)	68891-46-3		0.0003327	g	1000	0.1		689	0.0689
Die Encapsulant, Halogen-free		Plastics/polymers	Poly[o-cresyl glycidyl ether]-co-formaldehyde	29690-82-2		0.0073194	g	22000	2.2		15160	1.516
Die Encapsulant, Halogen-free		Plastics/polymers	Proprietary Material-Other Epoxy resins	-		0.019791	g	33000	3.3		22740	2.274
Die Encapsulant, Halogen-free		Solvents, additives, and other materials	Carbon Black	1333-86-4		0.0009861	g	3000	0.3		2067	0.2067
Die Encapsulant, Halogen-free		Plastics/polymers	Proprietary Material-Other phenolic resins	-		0.0143061	g	43000	4.3		29631	2.9631
Die Encapsulant, Halogen-free		Glass	Silicon dioxide	7631-86-9		0.013308	g	40000	4		27564	2.7564
Die Encapsulant, Halogen-free		Glass	Silica, vitreous	60676-86-0		0.3854566	g	858000	85.8		591270	59.127
Pb Glass Fit Semiconductor Di	0.0019				7c-1		g					
Pb Glass Fit Semiconductor Di		Lead/Lead Compounds	Lead (II) titanate	12060-00-3		0.00001972	g	10381	1.0381		40	0.004
Pb Glass Fit Semiconductor Di		Glass	Fibrous-glass-wool	65997-17-3		0.00001889	g	9943	0.9943		39	0.0039
Pb Glass Fit Semiconductor Di		Solvents, additives, and other materials	2,2,4-trimethyl-1,3-pentanediol-1-monoisobutyrate	25265-77-4		0.00001889	g	9943	0.9943		39	0.0039
Pb Glass Fit Semiconductor Di		Glass	Silicon, doped	-		0.0019425	g	969733	96.9733		3816	0.3816
Epoxy Die Attach	0.0016						g					
Epoxy Die Attach		Metals	Silver, metal	7440-22-4		0.001216	g	760000	76		2518	0.2518
Epoxy Die Attach		Plastics/polymers	Other Non-halogenated Epoxy resins	-		0.0000697	g	43560	4.356		144	0.0144
Epoxy Die Attach		Solvents, additives, and other materials	Polymethylene polyphenyl isocyanate (PAPI)	9016-87-9		0.00000816	g	5100	0.51		16	0.0016
Epoxy Die Attach		Metals	Dibutyltin dilaurate	77-58-7		0.00000054	g	340	0.034		1	0.0001
Epoxy Die Attach		Solvents, additives, and other materials	Alkanes, C14-16	90622-46-1		0.000224	g	140000	14		463	0.0463
Epoxy Die Attach		Plastics/polymers	1,3-Benzenedicarboxylic acid, polymer with 1,4-benzenedicarboxylic acid, 1,4-butanediol and hexanedi	66027-02-9		0.0000816	g	51000	5.1		169	0.0169
Bonding Wire, PdCu	0.0014						g					
Bonding Wire, PdCu		Metals	Copper, metal	7440-50-8		0.00138348	g	988200	98.82		2865	0.2865
Bonding Wire, PdCu		Metals	Gold, metal	7440-57-5		0.00000112	g	800	0.08		2	0.0002
Bonding Wire, PdCu		Metals	Palladium, metal	7440-05-3		0.0000154	g	11000	1.1		31	0.0031
Copper Lead Frame	0.1128						g					
Copper Lead Frame		Metals	Copper, metal	7440-50-8		0.10873412	g	963955	96.3955		225215	22.5215
Copper Lead Frame		Solvents, additives, and other materials	Phosphorus, elemental (not containing red allotrope)	7723-14-0		0.00009306	g	825	0.0825		192	0.0192
Copper Lead Frame		Metals	Iron, metal	7439-89-6		0.0026508	g	23500	2.35		5490	0.549
Copper Lead Frame		Lead/Lead Compounds	Lead	7439-92-1		0.00001918	g	170	0.017		39	0.0039
Copper Lead Frame		Metals	Silver, metal	7440-22-4		0.001128	g	10000	1		2336	0.2336
Copper Lead Frame		Metals	Tin, metal	7440-31-5		0.00003384	g	300	0.03		70	0.007
Copper Lead Frame		Metals	Zinc, metal	7440-66-6		0.000141	g	1250	0.125		292	0.0292
Silicon Semiconductor Die	0.0019						g					
Silicon Semiconductor Die		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%).	-		0.0000038	g	20000	2		78	0.0078
Silicon Semiconductor Die		Glass	Silicon, doped	-		0.001862	g	980000	98		3856	0.3856

LINKS	
MCD LINK	
NXP website	http://www.nxp.com
GENERAL ENVIRONMENTAL COMPLIANCE LINKS	
RoHS signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-ROHS-DECLARATION.pdf
China RoHS	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/china-rohs:ENV_CHINA_ROHS_STRATEGY
REACH signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-REACH-STATEMENT.pdf
ELV signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-ELV-STATEMENT.pdf
Conflict Minerals statement	http://www.nxp.com/files/corporate/doc/support_info/NXP-STATEMENT-CONFLICT-MINERALS.pdf
NXP ENVIRONMENTAL INFORMATION	
Environmental Compliance website	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization:ABUENVPRFPRDX
FAQ	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/eco-product-faqs:ENVIRON_FAQ
Technical Service Request	http://www.nxp.com/support/sales-and-support:SUPPORTHOME
LINKS TO BLANK IPC1752 FORMS	
Blank IPC1752 v1.1 Form	http://www.NXP.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf

IPC1752 XML LINKS

http://www.freescale.com/mcds/MC08XSF421EKR2_IPC1752_v11.xml

http://www.freescale.com/mcds/MC08XSF421EKR2_IPC1752A.xml